General purpose (dual digital transistor)

Datasheet

Parameter	DTr1 and DTr2
$V_{\sf CEO}$	50V
I <sub>C</sub>	100mA
R <sub>1</sub>	4.7kΩ

#### Features

- 1)Two DTC143T chips in a EMT or UMT or SMT package.
- 2)Mounting possible with EMT3 or UMT3 or SMT3 automatic mounting machines.
- 3)Transistor elements are independent, eliminating interference.
- 4) Mounting cost and area can be cut in half.

#### Outline

SOT-563	SOT-363
EMH3 (EMT6)	UMH3N (UMT6)
SOT-457	

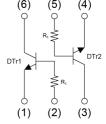
## •Inner circuit

#### EMH3 / UMH3N

**ІМН3А** 

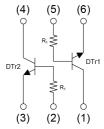
(SMT6)

- (1) DTr1 Emitter
- (2) DTr1 Base
- (3) DTr2 Collector
- (4) DTr2 Emitter
- (5) DTr2 Base
- (6) DTr1 Collector



#### IMH3A

- (1) DTr1 Collector
- (2) DTr2 Base
- (3) DTr2 Emitter
- (4) DTr2 Collector
- (5) DTr1 Base
- (6) DTr1 Emitter



## Application

INVERTER, INTERFACE, DRIVER

### Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
ЕМН3	SOT-563 (EMT6)	1616	T2R	180	8	8000	НЗ
UMH3N	SOT-363 (UMT6)	2021	TN	180	8	3000	НЗ
IMH3A	SOT-457 (SMT6)	2928	T110	180	8	3000	НЗ

## ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

<For DTr1 and DTr2 in common>

F	Parameter		Symbol	Values	Unit
Collector-base voltage			$V_{CBO}$	50	V
Collector-emitter voltage			V <sub>CEO</sub>	50	V
Emitter-base voltage		V <sub>EBO</sub>	5	V	
Collector current		I <sub>C</sub>	100	mA	
	EMH3		P <sub>D</sub> *1*2	150	
Power dissipation	UMH3N		P <sub>D</sub> *1*2	150	mW/Total
	IMH3A		P <sub>D</sub> *1*3	300	
Junction temperature		T <sub>j</sub>	150	°C	
Range of storage temperature			T <sub>stg</sub>	-55 to +150	°C

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

<For DTr1 and DTr2 in common>

Darameter	Cymabal	Conditions		Values			
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Unit	
Collector-base breakdown voltage	BV <sub>CBO</sub>	I <sub>C</sub> = 50μA	50	-	-	V	
Collector-emitter breakdown voltage	BV <sub>CEO</sub>	I <sub>C</sub> = 1mA	50	-	-	V	
Emitter-base breakdown voltage	BV <sub>EBO</sub>	I <sub>E</sub> = 50μA	5	-	-	V	
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 50V	-	-	500	nA	
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = 4V	-	-	500	nA	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 5mA, I <sub>B</sub> = 0.25mA	-	-	300	mV	
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> = 5V, I <sub>C</sub> = 1mA	100	250	600	-	
Input resistance	R <sub>1</sub>	-	3.29	4.7	6.11	kΩ	
Transition frequency	f <sub>T</sub> *4	V <sub>CE</sub> = 10V, I <sub>E</sub> = -5mA, f = 100MHz	-	250	-	MHz	

<sup>\*1</sup> Each terminal mounted on a reference land



<sup>\*2 120</sup>mW per element must not be exceeded.

<sup>\*3 200</sup>mW per element must not be exceeded.

<sup>\*4</sup> Characteristics of built-in transistor

## ● Electrical characteristic curves (T<sub>a</sub> = 25°C)

<For DTr1 and DTr2 in common>

Fig.1 Grounded Emitter Propagation Characteristics

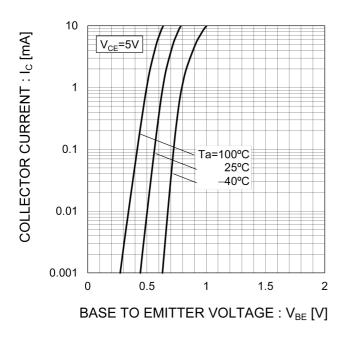


Fig.2 Grounded Emitter Output Characteristics

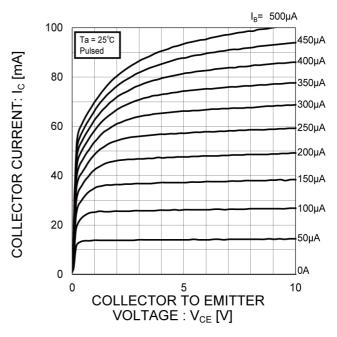


Fig.3 DC Current Gain vs. Collector Current

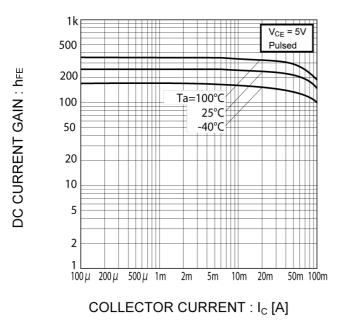
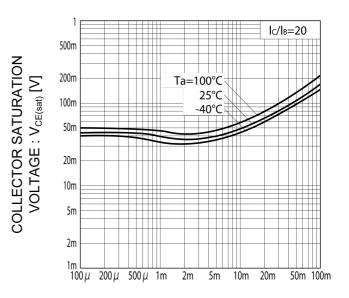
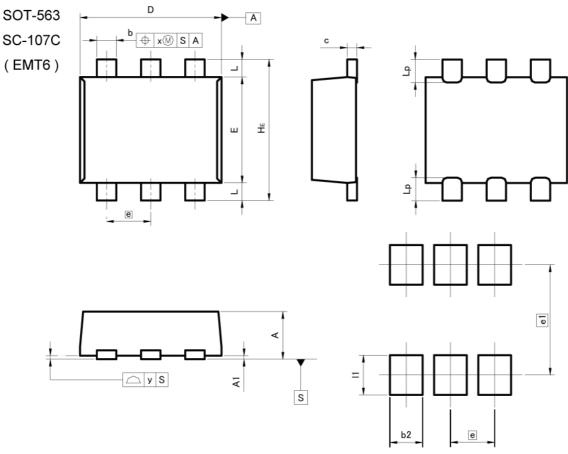


Fig.4 Collector-Emitter Saturation Voltage vs. Collector Current



COLLECTOR CURRENT: Ic [A]

## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

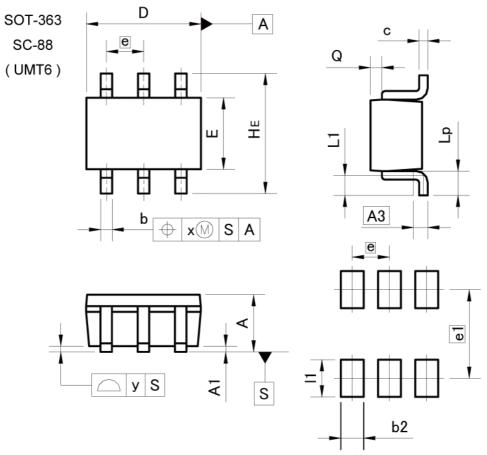
	MILIMETERS		INCHES	
DIM	IVITETIVI	ETERS	INCHES	
Diw	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	1.10	1.30	0.043	0.051
е	0.	50	0.0	20
HE	1.50	1.70	0.059	0.067
L	0.10	0.30	0.004	0.012
Lp	_	0.35	_	0.014
х	-	0.10	_	0.004
У	_	0.10	-	0.004

DIM MILIMETERS		ETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
b2	-	0.37	_	0.015	
e1	1.25		0.0	49	
- 11	-	0.45	-	0.018	

Dimension in mm/inches



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

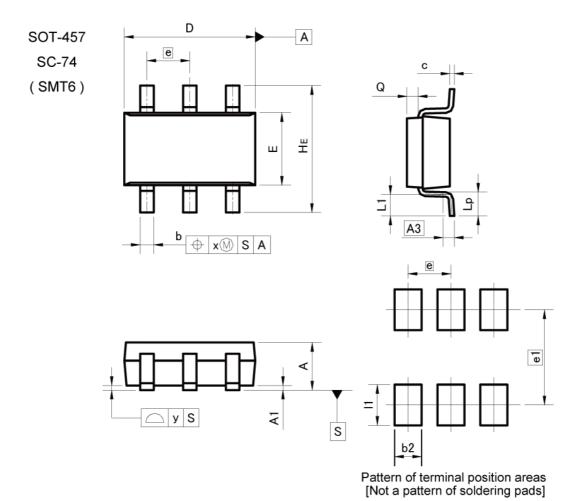
DIM	MILIM	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.3	25	0.0	10
b	0.15	0.30	0.006	0.012
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.65 0.026		26	
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
х	-	0.10	, <del>-</del>	0.004
У		0.10	e <del></del>	0.004

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
b2	- 7	0.40	-	0.016
e1	1.55		0.0	61
11	-	0.65	-	0.026

Dimension in mm/inches



## Dimensions



DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.:	25	0.0	10
b	0.25	0.40	0.010	0.016
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
Е	1.50	1.80	0.059	0.071
е	0.9	95	0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
х	-	0.20	-	0.008
У	-	0.10	-	0.004

D.114	MILIM	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
b2		0.60	<del>-</del>	0.024
e1	2.10		0.0	83
I1	>	0.90	<del>-</del>	0.035

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CL ACCIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [h] Use of the Products in places subject to dew condensation
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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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